AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (currently amended) A method for altering a surface feature of an existing pattern on an integrated circuit substrate, said method comprising

(a) locally delivering a chemical to a site proximate to a target feature of said existing pattern on an integrated circuit substrate to be altered, and

(b) providing activating energy at said site whereby a chemical reaction and/or milling occurs wherein said activating energy is provided by illuminating a probe tip proximate to said site, said probe tip comprising a non-metal portion and a metal apex portion which causes localized scattering of photons at said site,

said reaction and/or milling resulting in alteration of said target feature.

2. Canceled.

3. (previously presented) The method of claim 1 wherein said delivery is performed by passing said chemical through a probe tip channel having an opening placed proximate to said site.

4. (previously presented) The method of claim 1 wherein said delivery is performed by placing a probe tip coated with said chemical proximate to said site.

5. Canceled.

6. Canceled.

7. Canceled.

8. (currently amended) The method of claim 1~~7~~ wherein said apex is illuminated with an energy source of wavelength at least about ten times greater than a diameter of said apex.

9. Canceled.

10. Canceled.

11. (original) The method of claim 1 wherein a second chemical is provided for assisting in said reaction.

12. Canceled.

13. Canceled.

14. (currently amended) The method of claim 1~~7~~ wherein said scattering results in the imparting of thermal energy to said substrate at said site.

15 -30. Canceled.

31. (previously presented) The method of claim 1 wherein said feature and pattern are made of copper.

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